

Features

- IEC61000-4-2(ESD)±15KV(air), ±8KV(contact)
- IEC61000-4-4(FET) 40A (5/50ns)
- IEC61000-4-5(Lightning) 5A 8/20us
- Low clamping voltage
- Package optimized for high-speed lines
- Moisture sensitivity level: level 1
- Ultra-small package:DFN1006


Exterior

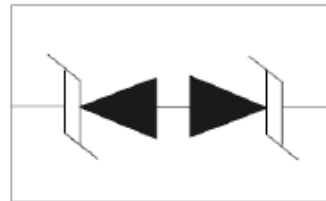
DFN1006
Application information

- Portable Electronics
- Desktops, Servers and Notebooks
- Cellular Phones
- Digital Ports
- Subscriber Identity Module (SIM) card
- Notebooks

Package (Top View)

Agency Approvals

ICoN	Description
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC 61249-2-21:2003
	Mean lead free

Schematic Symbol

Part Number and Electrical Parameter

Part Number	I _{DRM} @V _{DRM}		V _{BR} @I _{BR}		V _C @I _{PP} ^①		V _C @I _{PP} ^①		C ₀ ^②
	uA	V	V	mA	V	A	V	A	pF
	MAX		MIN		MAX		MAX		TYP
BV-FA05ZC	1.0	5.0	6.0	1.0	9.5	1.0	15.0	5.0	10

Absolute maximum rating measured at T=25°C RH=45%-75% (unless otherwise noted).

① Surge Waveform: 8/20us;

② Off-state capacitance is measured in V_{BR}=0V, f=1MHz;

Transient Voltage Suppressor
Part Number System

BV FA05ZC

(1) (2)

(1) Bencent TVS

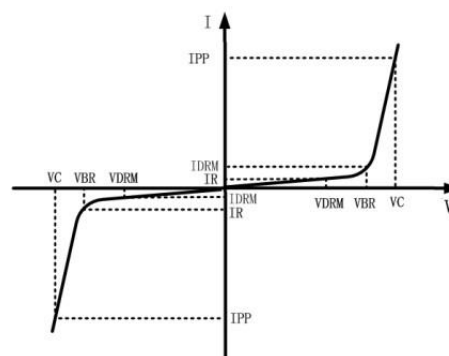
(2) Series: FA05ZC etc.

Mark


PB: Marking

V-I Curve

Parameters	Definition
V_C	Clamping voltage
I_{PP}	Peak pulse current
V_{DRM}	Stand-off Voltage
V_{BR}	Breakdown Voltage
I_{DRM}	Reverse Leakage Current
I_R	Test current
P_{PP}	Peak Pulse Power Dissipation


Thermal Considerations

Symbol	Parameter	Value	Unit
T_J	Operating Junction Temperature Range	-55 to +150	°C
T_S	Storage Temperature Range	-55 to +150	°C

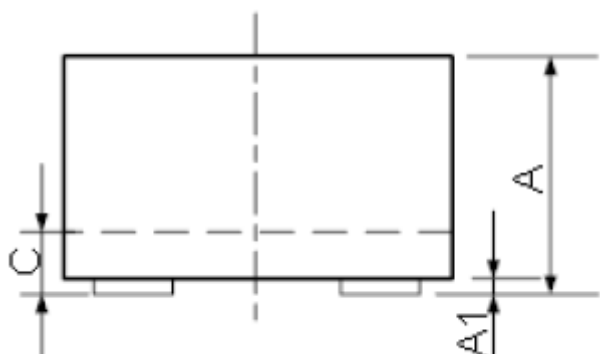
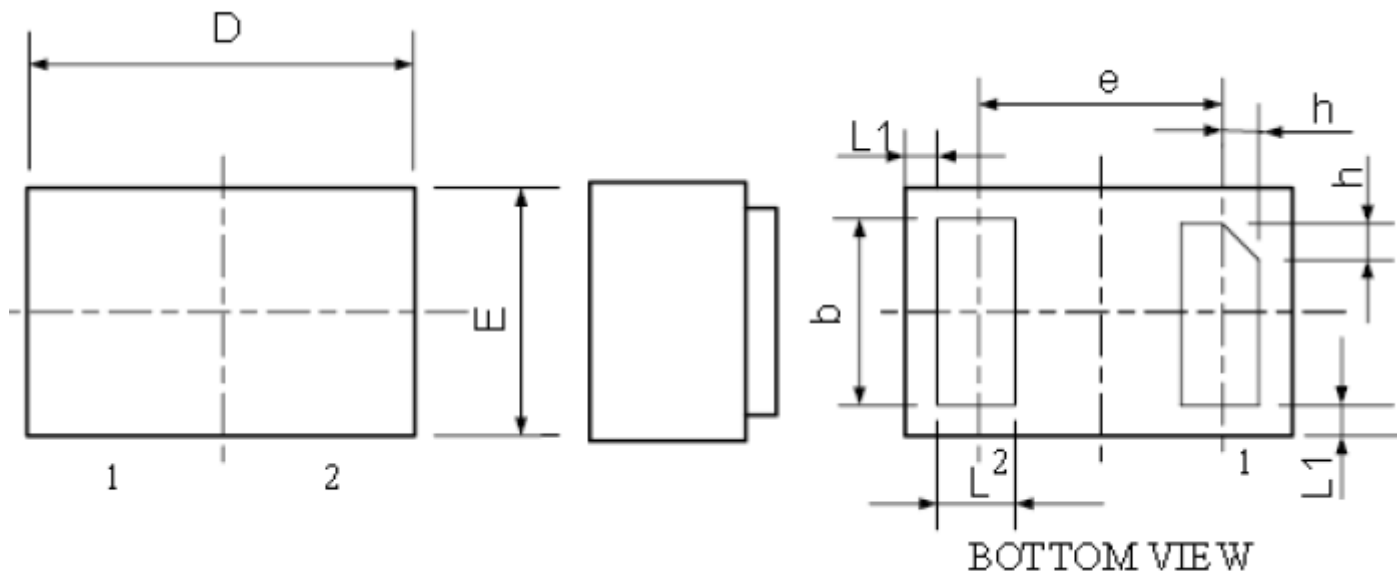
Environmental Characteristics

Testing Items	Technical Standards
High Temperature Reverse Bias Test	Temperature: $150 \pm 3^\circ\text{C}$, Bias = $80\% V_{DRM}$ Time: 168H
High Temperature Life Test	Temperature: 150°C Time: 168H
High-low Temperature Cycle Test	Temperature: From -40°C to 125°C Dwell time: 30min, 100 cycles
High Temperature & High Humidity Test	Temperature: 85°C Humidity: 85% Test time: 168H
Pressure Cooker Test	Temperature: 121°C , 2atm. Humidity: 100% Test time: 24H
Resistance of Soldering Heat	Temperature: $260 \pm 5^\circ\text{C}$ Time of dip soldering: 10s, 3 times

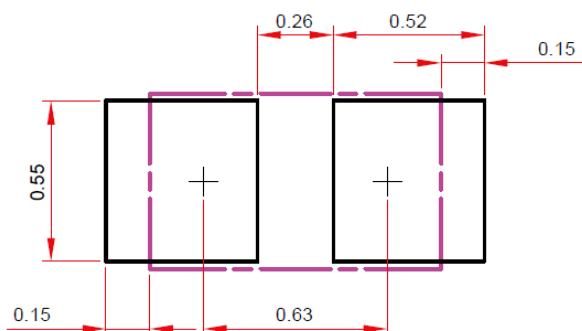
Note: The above testing items can be specified by customers by contacting Bencent service

Product Dimensions

DFN1006



Recommended Soldering Pad



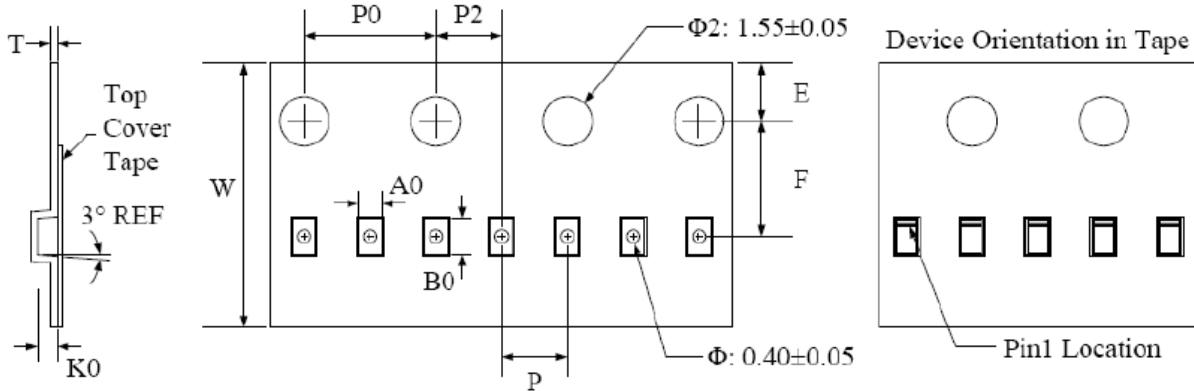
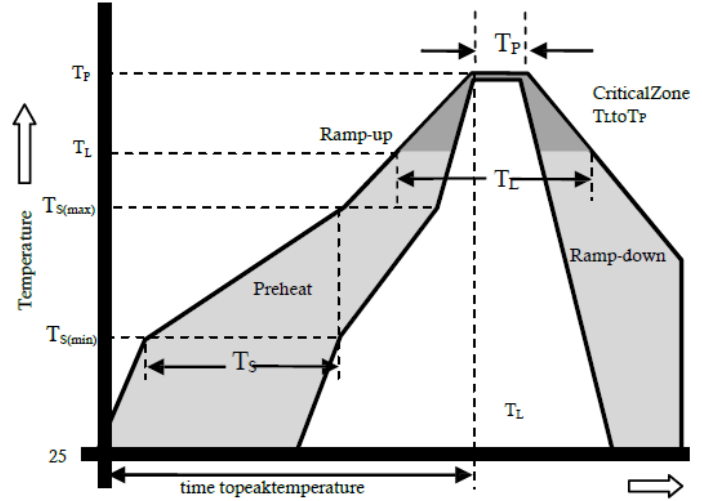
Symbol	Dimensions In Millimeters	
	Minimum	Maximum
A	0.450	0.550
A1	0.000	0.050
b	0.45	0.55
C	0.12	0.18
D	0.950	1.050
e	0.65BSC	
E	0.550	0.650
L	0.200	0.300
L1	0.05REF	
h	0.07	0.17

Transient Voltage Suppressor

Version: A0 2016-05-10

Reflow Profile

Reflow Condition		Pb-Free Assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time (Min to Max)	20 – 80 secs
Average ramp up rate (Liquid)		3°C/s Max.
Temperature (T _L) to peel		3°C/s Max.
T _S (Max) to T _I -Ramp-up Rate		3°C/s Max.
Reflow	-Temperature (T _L)(Liquid)	217°C
	-Temperature (T _I)	60 – 150 secs
Peak Temperature (T _P)		(260+0/-5)°C
Time within 5°C of actual Peak Temperature (T _P)		8– 15 secs
Ramp-down Rate		6°C/s Max.
Time 25°C to peak Temperature(T _P)		8 min Max
Do not exceed		260°C



Symbol	W	A0	B0	K0	E	F	P	P0	P2	T
Dimensions (mm)	8.00±0.1	0.7±0.05	1.15±0.05	0.55±0.05	1.75±0.1	3.5±0.05	2.0±0.1	4.0±0.1	2.0±0.05	0.2±0.05

Package Reel Information

Outline	Reel (pcs)	Per Carton (pcs)	Reel Diameters (mm)	Carton Size (mm)		
				L	W	H
Taping	10,000	90,000	178	390	370	220

单击下面可查看定价，库存，交付和生命周期等信息

[>>Bencent \(槟城\)](#)